EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6352	(257/750,759,778,785).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/01/29 15:04
L2	2823	L1 and ("wiring board" "circuit board" "wiring substrate" interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/01/29 15:06
L3	1820	L2 and ("flip chip" "chip-on-chip" cob "chip-on-board")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/01/29 15:08
L4	1113	L3 and ("flip chip" "chip-on-chip" cob "chip-on-board") near5 (ball bump "solder ball" solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/01/29 15:11
L5	6	L4 and (ball bump "solder ball" solder) near5 ((sharp cone conical needle pin) near3 tip)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/01/29 15:14
L6	585273	("wiring board" "circuit board" "wiring substrate" interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/01/29 15:17
L7	23798	L6 and ("flip chip" "chip-on-chip" cob "chip-on-board")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/01/29 15:17
L8	9305	L7 and ("flip chip" "chip-on-chip" cob "chip-on-board") near5 (ball bump "solder ball" solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/01/29 15:17
L9	37	L8 and (ball bump "solder ball" solder) near5 ((sharp cone conical needle pin) near3 tip)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/01/29 15:17
L10	28	L9 and @ad<"20031006"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/01/29 15:18

1/29/2009 3:43:15 PM
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